

# MSKSEMI

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Product data sheet

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**FEATURES**

- Small Package
- Low Reverse Current
- Fast Switching Speed
- Surface Mount Package Ideally Suited for Automatic Insertion

**MARKING: T5**

SOD-323



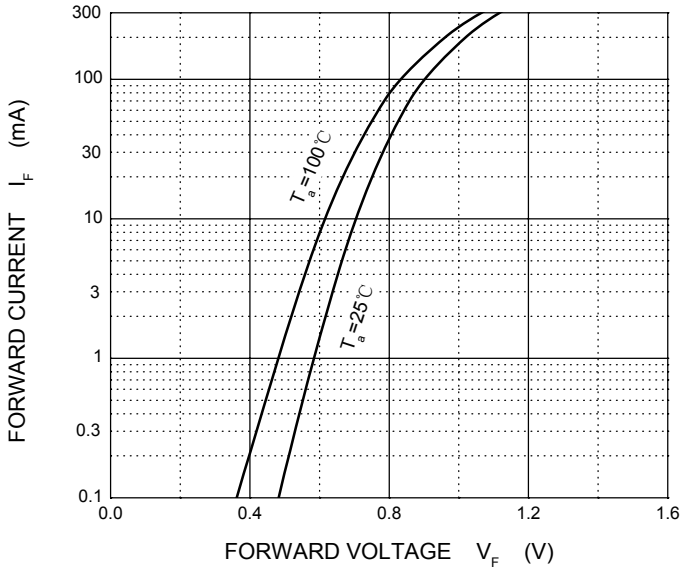
**Maximum Ratings and Electrical Characteristics, Single Diode @Ta=25°C**

Parameter	Symbol	Limit	Unit
Non-Repetitive Peak Reverse Voltage	$V_{RM}$	100	V
Peak Repetitive Peak Reverse Voltage	$V_{RRM}$	75	V
Working Peak Reverse Voltage	$V_{RWM}$		
DC Blocking Voltage	$V_R$		
RMS Reverse Voltage	$V_{R(RMS)}$	53	V
Forward Continuous Current	$I_{FM}$	500	mA
Average Rectified Output Current	$I_O$	250	mA
Non-Repetitive Peak Forward Surge Current @t=8.3ms	$I_{FSM}$	2.0	A
Power Dissipation	$P_d$	200	mW
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	625	°C/W
Operation Junction and Storage Temperature Range	$T_J, T_{STG}$	-55~+150	°C

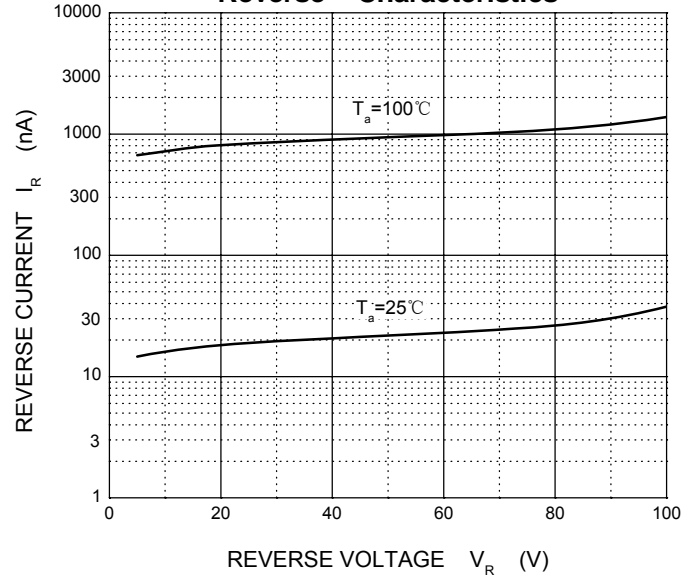
**Electrical Ratings @Ta=25°C**

Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Reverse Breakdown Voltage	$V_{(BR)R}$	75			V	$I_R=10\mu A$
Forward Voltage	$V_{F1}$	0.62		0.72	V	$I_F=5mA$
	$V_{F2}$			0.855	V	$I_F=10mA$
	$V_{F3}$			1.0	V	$I_F=100mA$
	$V_{F4}$			1.25	V	$I_F=150mA$
Reverse Current	$I_{R1}$			2.5	$\mu A$	$V_R=75V$
	$I_{R2}$			25	nA	$V_R=20V$
Capacitance Between Terminals	$C_T$			4	pF	$V_R=0V, f=1MHz$
Reverse Recovery Time	$t_{rr}$			4	ns	$I_F=I_R=10mA$ $I_{rr}=0.1X I_R, R_L=100\Omega$

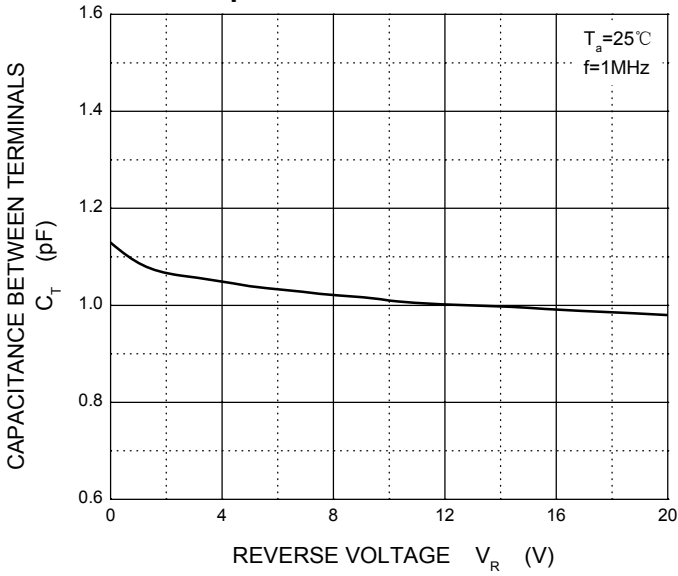
**Forward Characteristics**



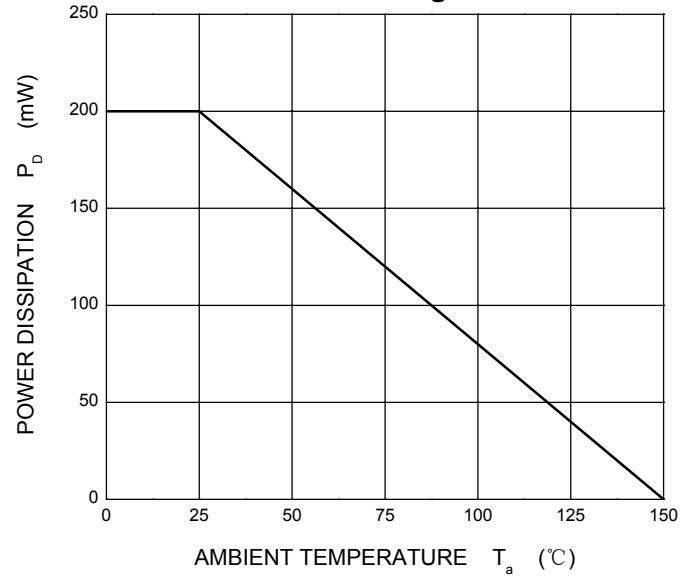
**Reverse Characteristics**



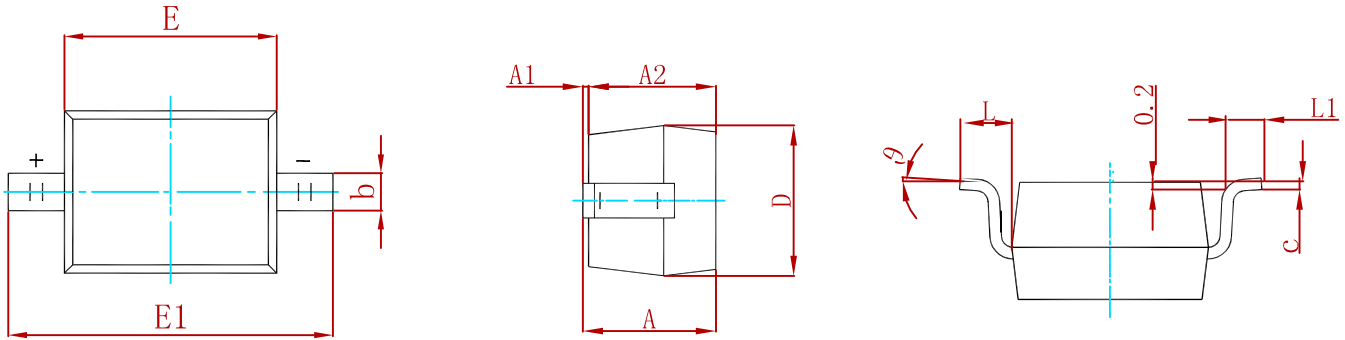
**Capacitance Characteristics**



**Power Derating Curve**

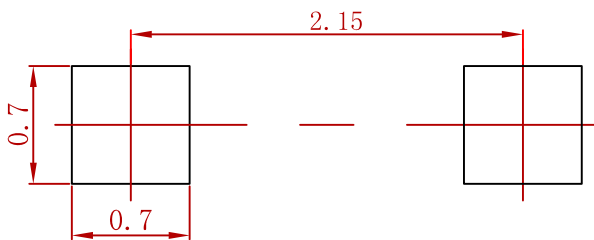


**PACKAGE MECHANICAL DATA**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A		1.000		0.039
A1	0.000	0.100	0.000	0.004
A2	0.800	0.900	0.031	0.035
b	0.250	0.350	0.010	0.014
c	0.080	0.150	0.003	0.006
D	1.200	1.400	0.047	0.055
E	1.600	1.800	0.063	0.071
E1	2.550	2.750	0.100	0.108
L	0.475 REF.		0.019 REF.	
L1	0.250	0.400	0.010	0.016
θ	0°	8°	0°	8°

**Suggested Pad Layout**



**Note:**

1. Controlling dimension: in millimeters.
2. General tolerance:  $\pm 0.05\text{mm}$ .
3. The pad layout is for reference purposes only.

**REEL SPECIFICATION**

P/N	PKG	QTY
1N4448WS	SOD-323	3000

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